

Claims

Claim 1

A latex for dip molding, which is obtainable by emulsion polymerization of 100 parts by weight of a monomer mixture in the presence of 0.5 to 10.0 parts by weight of alkyl benzene sulfonate containing at least 10 weight % of C₁₃₋₂₀ alkyl benzene sulfonate.

Claim 2

The latex for dip molding according to claim 1, wherein the alkyl benzene sulfonate contains at least 25 weight % of C₁₃₋₂₀ alkyl benzene sulfonate.

Claim 3

The latex for dip molding according to claim 1, wherein the alkyl benzene sulfonate contains at least 40 weight % of C₁₃₋₂₀ alkyl benzene sulfonate.

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Claim 4

The latex for dip molding according to any one of claims 1 to 3, wherein the emulsion polymerization is conducted by the use of redox type of polymerization initiator containing no transition metal salt.

Claim 5

The latex for dip molding according to claim 4, wherein the redox type polymerization initiator containing no transition metal salt is a combination product of an oil-soluble peroxide with a reducing agent.

Claim 6

The latex for dip molding according to claim 5, wherein the reducing agent is an alkali metal sulfonate or ammonium sulfonate.

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Claim 7

The latex for dip molding according to claim 6, wherein the alkali metal sulfonate is sodium formaldehyde sulfoxylate.

Claim 8

The latex for dip molding according to any one of claims 1 to 7, wherein 100 parts by weight of the monomer mixture comprises 15 to 45 parts by weight of a vinyl cyanide monomer, 35 to 80 parts by weight of a conjugated diene monomer, 0.1 to 20 parts by weight of an ethylenically unsaturated carboxylic acid, and 0 to 20 parts by weight of other ethylenically unsaturated monomer copolymerizable with the above monomers.

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Claim 9

The latex for dip molding according to any one of claims 1 to 8, wherein the emulsion polymerization of the monomer mixture is carried out in the presence of a seed polymer having an average particle diameter of 10 to 90 nm and a glass transition temperature (T_g) of -50 to 50 °C obtained by emulsion polymerization of a vinyl cyanide monomer and an ethylenically unsaturated monomer copolymerizable therewith.

Claim 10

A dip molded product produced by dip molding from the latex for dip molding described in any one of claims 1 to 9.

Claim 11

The dip molded product according to claim 10, which is a glove or a fingerstalls.